

GENERAL INFORMATION
General information

Typology	Gold solder
Color	White
Color shade	Off-white
Production process	Brazing
Grain refinement level	Minimum
Deoxidation level	Minimum

Commercial composition (%)

CU	34.0
ZN	35.0
NI	10.0
AG	12.0
IN	9.0

Melting Temperatures

Solidus [°C]	695.0
Liquidus [°C]	785.0
Melting range [°C]	90.0

FULL CHARACTERIZATION DATA
Color coordinates

L *	a*	b*	c*	Yellow Index
84.6	-0.5	14.4	14.4	27.5

Mechanical characteristics

As cast hardness [HV 0.2]	190.0
Tensile strength (Rm) [Mpa]	422.0
Yield strength (Rp0.2) [MPa]	332.0
Elongation at rupture (A) [%]	43.0

Physical characteristics

Density [g/cm ³]	14.3
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General characteristics

As cast grain size [μm]	230.0
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Product applications

LSB475A 750‰

MASTER ALLOY FOR SOLDERING OF 750‰ (18 KT) WHITE GOLD

MECHANICAL WORKING PARAMETERS
Pre-melting temperature

Temperature [°C] 905

Reductions

Wire - diameter (%)	30.0
Sheet - area or thickness (%)	50.0

POURING TEMPERATURES

Countinous from [°C]

Countinous to [°C]

Ingot to [°C]

Ingot from [°C]

Temperatures

885

965

865

905

MECHANICAL WORKING ANNEALING

Temp. from [°C]

Temp. to [°C]

Time [min]

< 1 mm

530

560

20

> 5 mm

530

560

25

1 - 5 mm

530

560

30

Mechanical working quenching

Air cool down to 550°C, then quench in 50%/50% water/alcohol solution or in water.

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Preliminary checks

Please note that in order to correctly evaluate the alloy's hardness to solderability, it is advised to make a numerical calculation by subtracting the base metal solidus temperature value from the solder liquidus temperature value. The higher the number resulting, the more solderable (or the less hard) the alloy can be considered. Please refer to the technical guideline for solders available in the website for further information.